

2006/09/25

# Qualification Report

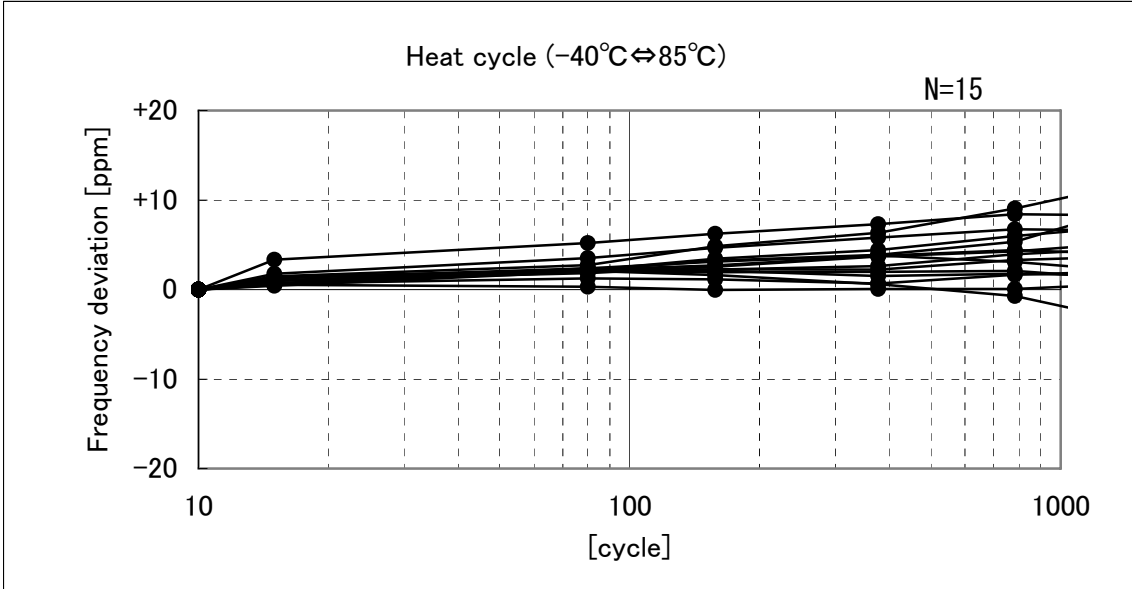
## J-LEAD VCX0/PX0 (HFF-X38 USED) (TCO-2000, 3000 Series)

1. Heat cycle test
2. Operating life test
3. High temperature and humidity test
4. Humidity test
5. Low temperature test
6. Drop test
7. Vibration test
8. ESD test
9. Solder heat resistance , reflow
10. Solder heat resistance , solder iron
11. Solderability
12. Mechanical shock test

EPSON TOYOCOM CORPRATION		
APP.	CHK'D	DRAW
Y. AOYAGI		K. MORITA

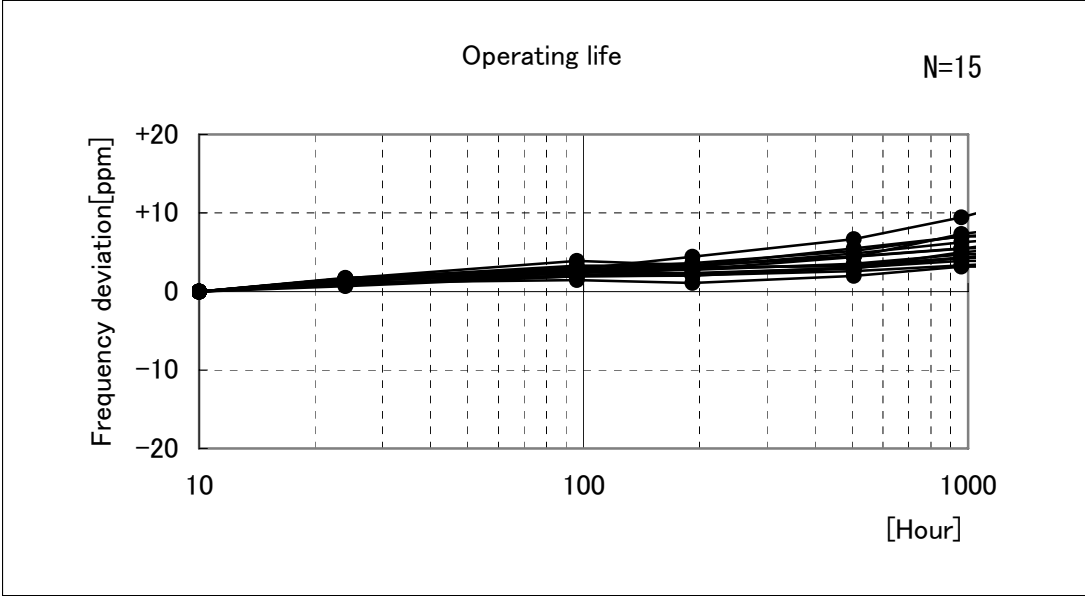
**1. Heat cycle test**

-40[°C] ↔ +85[°C] (each 30min. 1cycle) 1000cycles



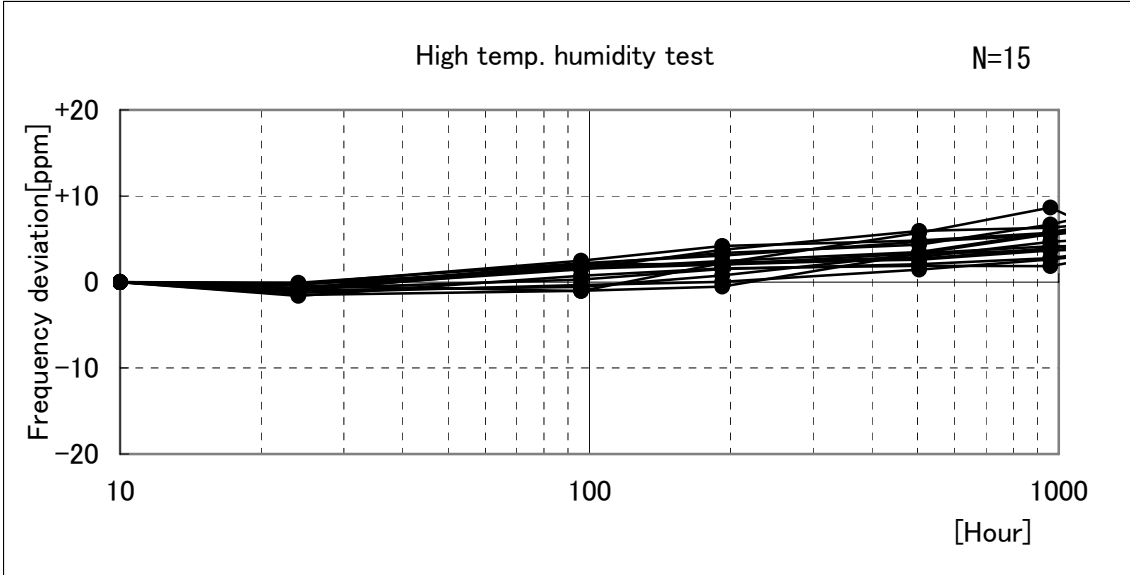
2. Operating life test

+85[°C], Supply voltage +3.63[V] 1000H



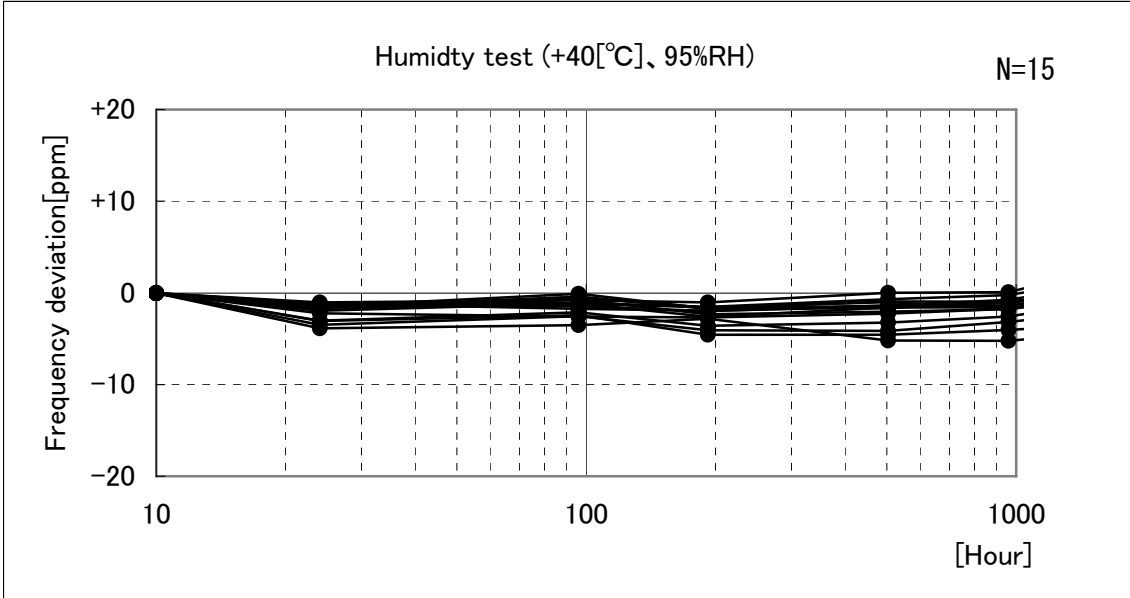
3. High temperature and humidity test

+85[°C], 85%RH, Suplly voltage +3. 63[V] 1000H



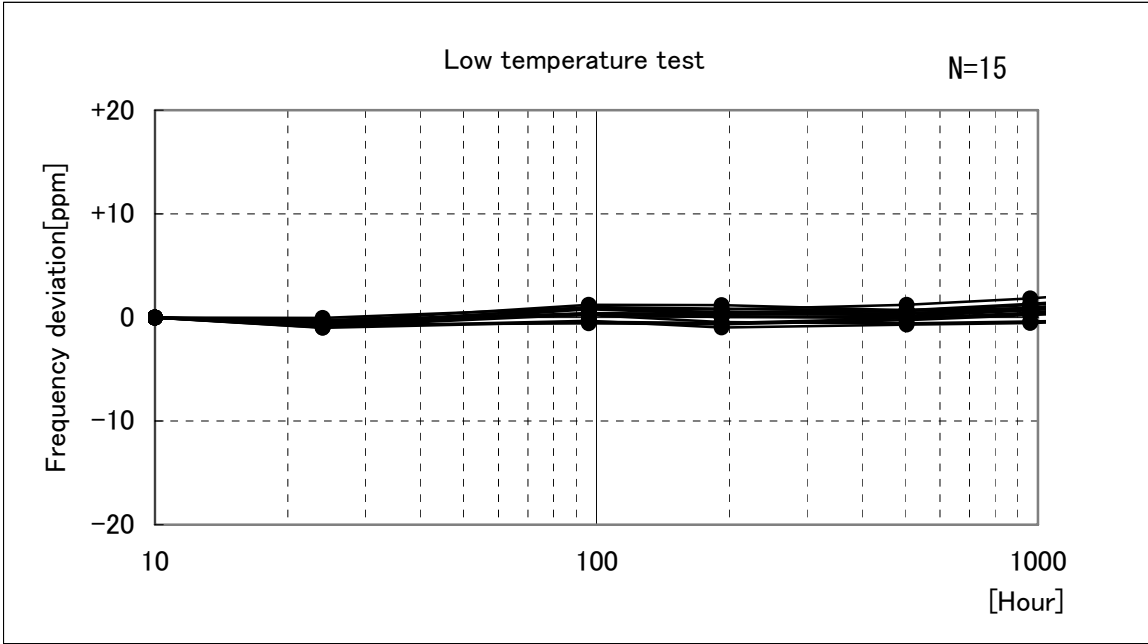
**4. Humidity test**

+40[°C]、95%RH 1000H



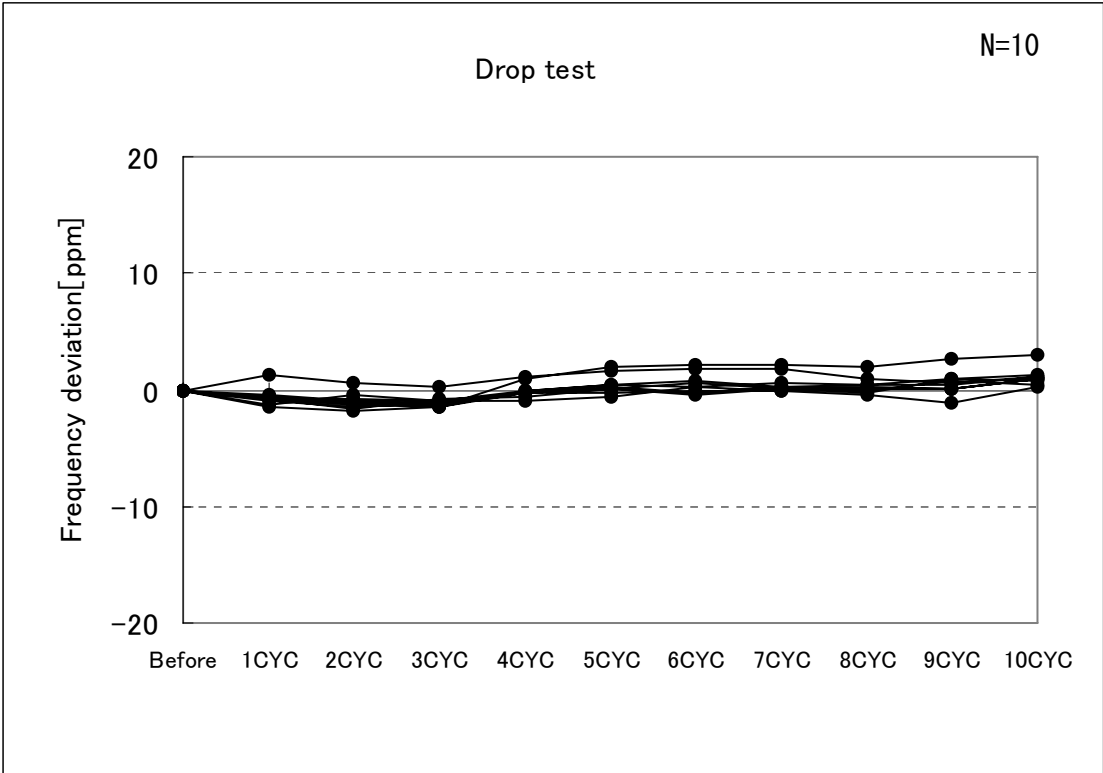
**5. Low temperature test**

-40[°C], 1000H



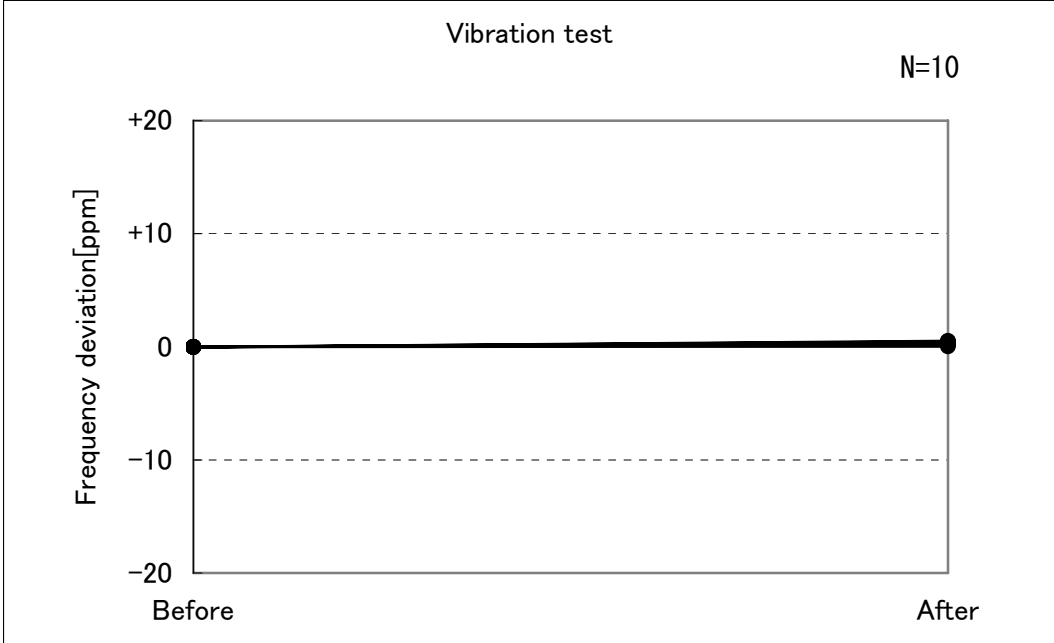
**6. Drop test**

On to wood plate from 750mm height  
1cycle=3 directions, 10cycles



**7. Vibration test**

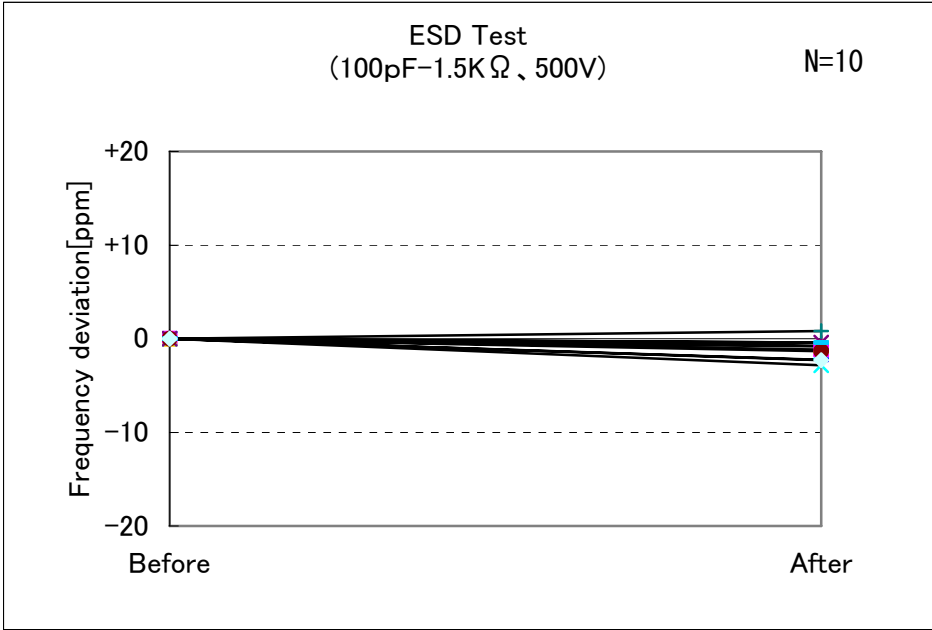
10 to 85[Hz] 1.5[mm] amplitude and 85 to 2000[Hz] 20[G]  
Vibrate in 3 mutually perpendicular planes each 2hours



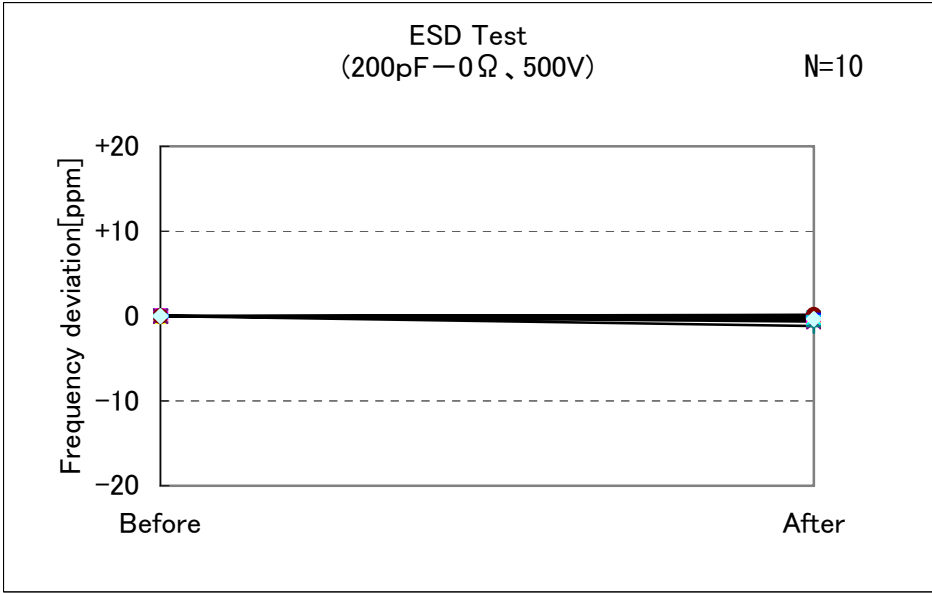


**8. ESD test**

Human Model : 100pF-1.5KΩ, 500V, 3Times/pin

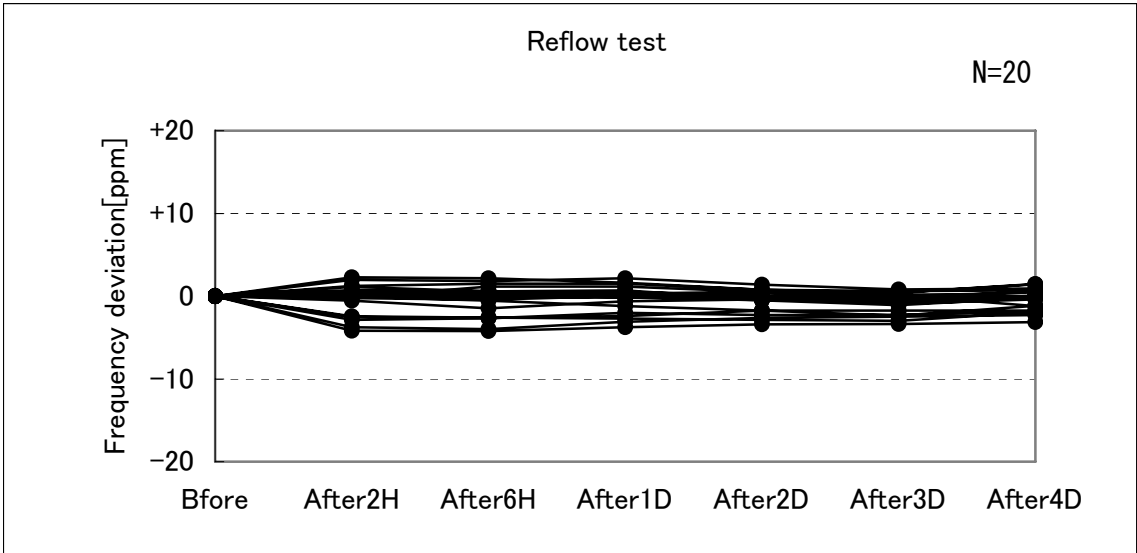
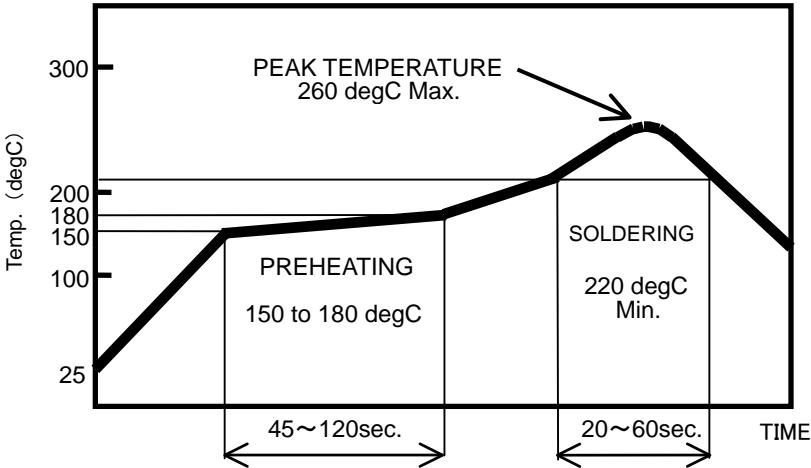


Machine Model : 200pF-0Ω, 500V, 3times/pin



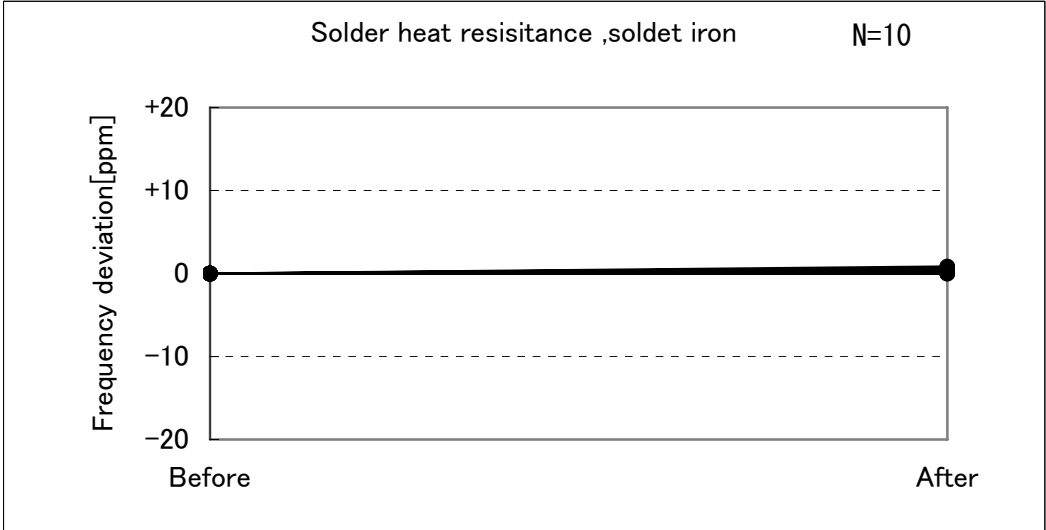
**9. Solder heat resistance , reflow**

2times below reflow soldering profile.



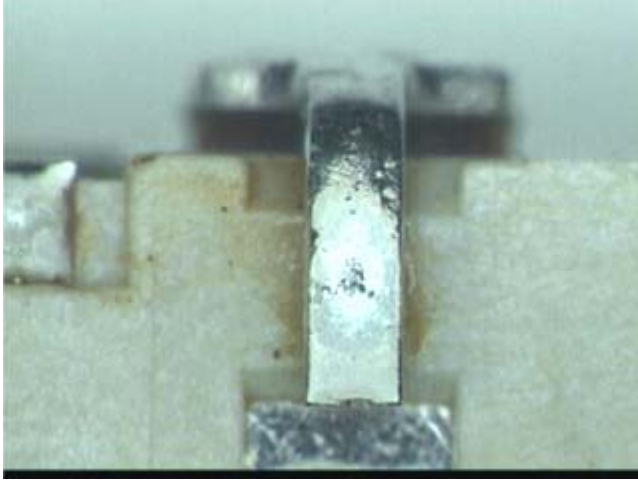
10. Solder heat resistance ,solder iron

350°C、5second/pin×6pin Measure 1 hour after test



**11. Solderability**

235°C、3second (Pb Free solder)



**12. Mechanical shock test**

3000[G]、5000[G] 1minute 3times/direction×6directions

